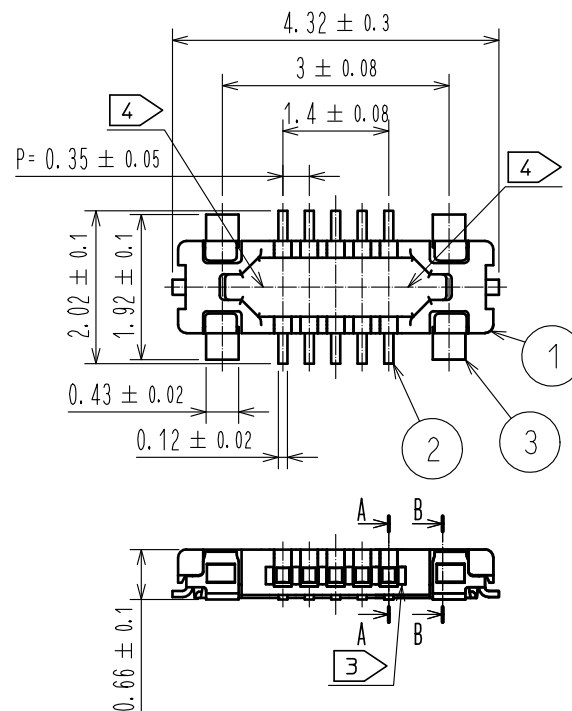




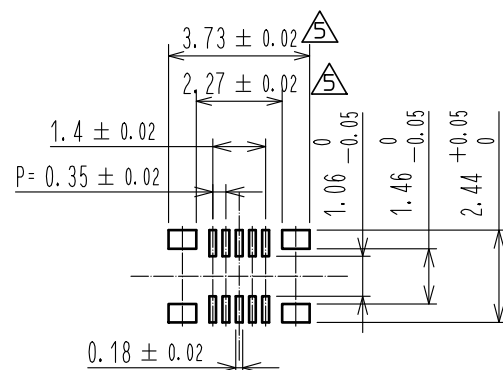
NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.

2 CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD $0.05 \mu\text{m}$ MIN
SMT LEAD : GOLD $0.05 \mu\text{m}$ MIN
UNDER PLATING : NICKEL $1 \mu\text{m}$ MIN
(SURFACE : SEALING)

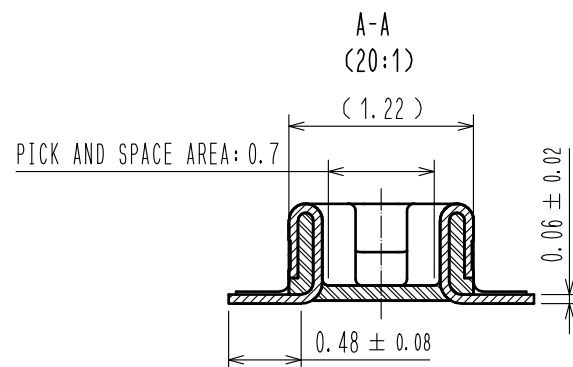
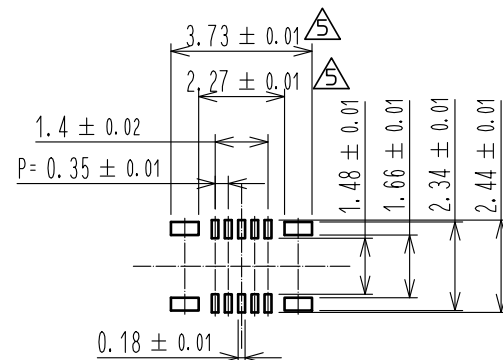
3 A PART OF THE WALL COULD BE NOTCHED.

4 HRS MARK AND CAV No. ARE INDICATED IN APPROX. POSITION SHOWN.

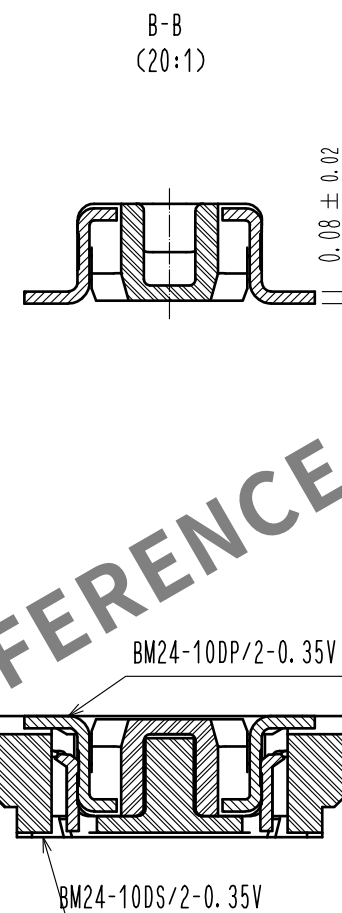
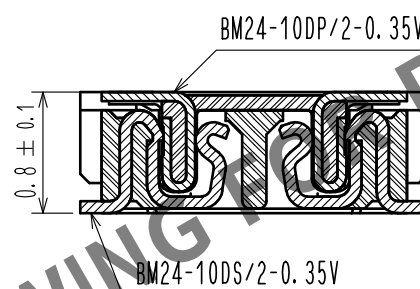
◆RECOMMENDED PCB LAYOUT



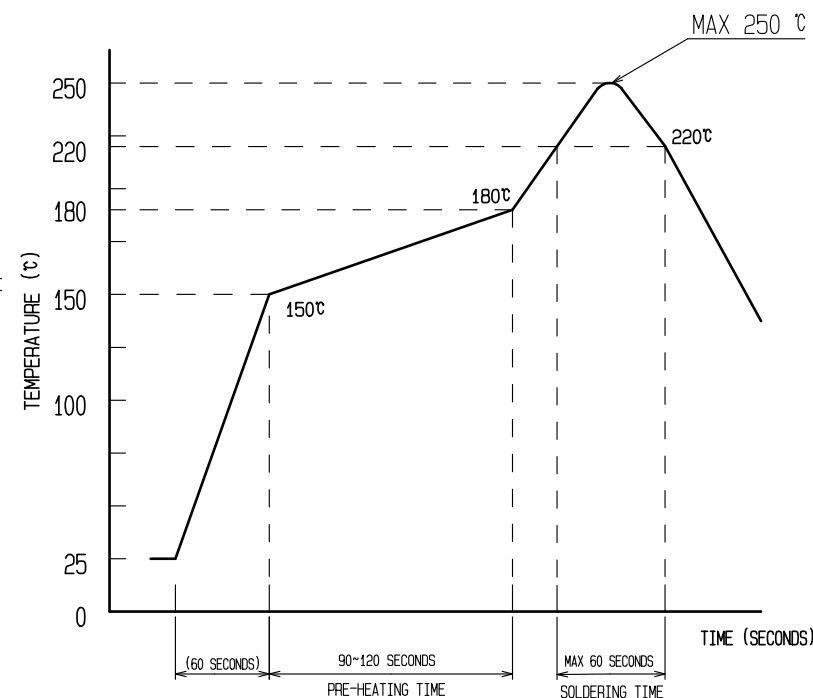
◆RECOMMENDED METAL MASK DIMENSIONS
METAL MASK THICKNESS : $100 \mu\text{m}$



ENGAGEMENT FIGURE (20:1)



5 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE (MIN): 150°C
PRE-HEAT TEMPERATURE (MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING COONDITION IS REQUIRED PRIOR TO PRODUCTION. TEPERATURE IS MEASURED AT CONTACT LEAD.
6. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	COPPER ALLOY	2	7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0. BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 10 : 1	COUNT 4	DESCRIPTION OF REVISIONS DIS-H-00001151	DESIGNED NY. YAMASHIRO
		APPROVED : KH. IKEDA	13.11.06	DRAWING NO.	EDC3-352539-01
		CHECKED : WR. FUKUCHI	13.11.06	PART NO.	BM24-10DP/2-0.35V(51)
		DESIGNED : YH. HASEGAWA	13.11.06	CODE NO.	CL677-2001-9-51
		DRAWN : YH. HASEGAWA	13.11.06		
		DATE	15.12.03		

